

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	375	(264/211.21). CQLS	US-PGPUB; USPAT; USOCR	OR	OFF	2008/04/22 10:23
L2	3	1 and (semiconductor or semi?conductor)	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/04/22 10:24
S1	752539	semiconductor or semi- conductor	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/04/15 08:06
S2	2197561	knead\$3 or blend\$3 or stir \$4 or blend\$3 or mix\$3	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/04/15 08:11
S3	11198021	@pd< "20030201"	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/04/15 08:20
S4	749029	volatile or vaporous or gaseous	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/04/15 08:23
S5	14632	S1 and S2 and S3 and S4	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/04/15 08:25
S6	1180198	vacuum\$3 or suction\$3	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/04/15 08:27
S7	7791	S5 and S6	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/04/15 08:28
S8	1	("5930652").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/04/15 08:40
S9	14413	(chip adj scale adj package \$4) or (chip size package \$4) or csp	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/04/15 08:41
S10	6	encapsulet\$3	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/04/15 08:42
S11	261249	encapsulat\$3	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/04/15 08:43
S12	107	S1 near S11 and S2 and S3 and S4	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/04/15 08:44
S16	1185643	semiconductor or semi- conductor	JPO; DERWENT	ADJ	ON	2008/04/15 09:07
S17	1806059	knead\$3 or blend\$3 or stir \$4 or blend\$3 or mix\$3	JPO; DERWENT	ADJ	ON	2008/04/15 09:07
S18	18309706	@pd< "20030201"	JPO; DERWENT	ADJ	ON	2008/04/15 09:07
S19	218959	volatile or vaporous or gaseous	JPO; DERWENT	ADJ	ON	2008/04/15 09:08
S20	650886	vacuum\$3 or suction\$3	JPO; DERWENT	ADJ	ON	2008/04/15 09:08
S21	7046	(chip adj scale adj package \$4) or (chip size package \$4) or csp	JPO; DERWENT	ADJ	ON	2008/04/15 09:08
S22	51276	encapsulat\$3	JPO; DERWENT	ADJ	ON	2008/04/15 09:08

S24	5	S16 near S22 and S17 and S18 and S19	JPO; DERWENT	ADJ	ON	2008/04/15 09:10
S27	196	S16 near S22 and S17 and S18	JPO; DERWENT	ADJ	ON	2008/04/15 09:14
S28	3828	kneading machine	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/04/15 10:14
S29	752539	semiconductor or semiconductor	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/04/15 10:15
S30	2197561	knead\$3 or blend\$3 or stir \$4 or blend\$3 or mix\$3	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/04/15 10:15
S31	11198021	@pd< "20030201"	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/04/15 10:15
S32	749029	volatile or vaporous or gaseous	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/04/15 10:15
S33	14632	S1 and S2 and S3 and S4	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/04/15 10:15
S34	1180198	vacuum\$3 or suction\$3	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/04/15 10:15
S35	7791	S5 and S6	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/04/15 10:15
S36	1	("5930652").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/04/15 10:15
S37	14413	(chip adj scale adj packag \$4) or (chip size packag \$4) or csp	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/04/15 10:15
S38	6	encapsulat\$3	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/04/15 10:15
S39	261249	encapsulat\$3	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/04/15 10:15
S40	107	S1 near S11 and S2 and S3 and S4	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/04/15 10:15
S41	1185643	semiconductor or semiconductor	JPO; DERWENT	ADJ	ON	2008/04/15 10:15
S42	1806059	knead\$3 or blend\$3 or stir \$4 or blend\$3 or mix\$3	JPO; DERWENT	ADJ	ON	2008/04/15 10:15
S43	218959	volatile or vaporous or gaseous	JPO; DERWENT	ADJ	ON	2008/04/15 10:15
S44	650886	vacuum\$3 or suction\$3	JPO; DERWENT	ADJ	ON	2008/04/15 10:15
S45	7046	(chip adj scale adj packag \$4) or (chip size packag \$4) or csp	JPO; DERWENT	ADJ	ON	2008/04/15 10:15
S46	51276	encapsulat\$3	JPO; DERWENT	ADJ	ON	2008/04/15 10:15
S47	5	S16 near S22 and S17 and S18 and S19	JPO; DERWENT	ADJ	ON	2008/04/15 10:15
S48	196	S16 near S22 and S17 and S18	JPO; DERWENT	ADJ	ON	2008/04/15 10:15

S49	3828	kneading machine	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/04/15 10:15
S65	2	p-2001081284-\$ did.	FPRS, JPO, DERWENT	ADJ	ON	2008/04/15 13:33
S66	0	p-3320354	JPO, DERWENT	ADJ	ON	2008/04/15 13:36
S67	1	p-3320354-\$ did.	JPO, DERWENT	ADJ	ON	2008/04/15 13:36
S68	1	p-3009027-\$ did.	JPO, DERWENT	ADJ	ON	2008/04/15 13:43
S69	0	p-6-293021-\$ did.	JPO; DERWENT	ADJ	ON	2008/04/15 13:45
S70	0	p-6293021-\$ did.	JPO; DERWENT	ADJ	ON	2008/04/15 13:45
S71	0	p-0293021-\$ did.	JPO; DERWENT	ADJ	ON	2008/04/15 13:46
S72	0	p-293021-\$ did.	JPO; DERWENT	ADJ	ON	2008/04/15 13:46
S73	20616	biaxial	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/04/15 13:53
S74	250733	extrusion	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/04/15 13:53
S75	208	S73 near S74	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/04/15 13:53
S76	106	S73 near S74 and S3	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/04/15 13:55
S77	0	S73 near S74 and S3	JPO; DERWENT	ADJ	ON	2008/04/15 14:06
S78	79	biaxial near extrusion and @pd<"20030201"	JPO, DERWENT	ADJ	ON	2008/04/15 14:07
S79	0	biaxial near S30 and S31	JPO, DERWENT	ADJ	ON	2008/04/15 14:34
S80	344	biaxial near S42 and @pd<"20020201"	JPO, DERWENT	ADJ	ON	2008/04/15 14:43
S81	415	biaxial near S42 and @pd<"20030201"	JPO; DERWENT	ADJ	ON	2008/04/15 14:43
S82	11	S81 and S19	JPO; DERWENT	ADJ	ON	2008/04/15 14:44
S83	0	p-6293021-\$ did.	JPO; DERWENT	ADJ	ON	2008/04/16 08:13
S84	0	p-5104947-\$ did.	JPO; DERWENT	ADJ	ON	2008/04/16 08:14
S85	6945	@pd= "19941021"	JPO, DERWENT	ADJ	ON	2008/04/16 08:22
S86	2	jp?06293021?? did.	JPO, DERWENT	ADJ	ON	2008/04/16 08:24
S87	2	("2543181").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/04/16 08:42

S88	0	noborakku	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/04/16 11:49
S89	0	noborakku	US-PGPUB; USPAT; USOCR; JPO; DERWENT	ADJ	ON	2008/04/16 11:49
S90	0	(2002/0195725).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/04/16 12:18
S91	459	epoxy and resin and (inorganic or silica) and ((semiconductor or semi? conductor) near5 encapsul \$3) and @pd<"20030201"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/16 12:34
S92	0	(10/526008).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/04/17 06:26
S93	0	("10526008").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/04/17 06:27
S94	1	("20060017188").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/04/17 06:29

4/ 22/ 2008 10:27:48 AM

C:\Documents and Settings\dbrown\My Documents\EAST\Workspaces\10526008.wsp